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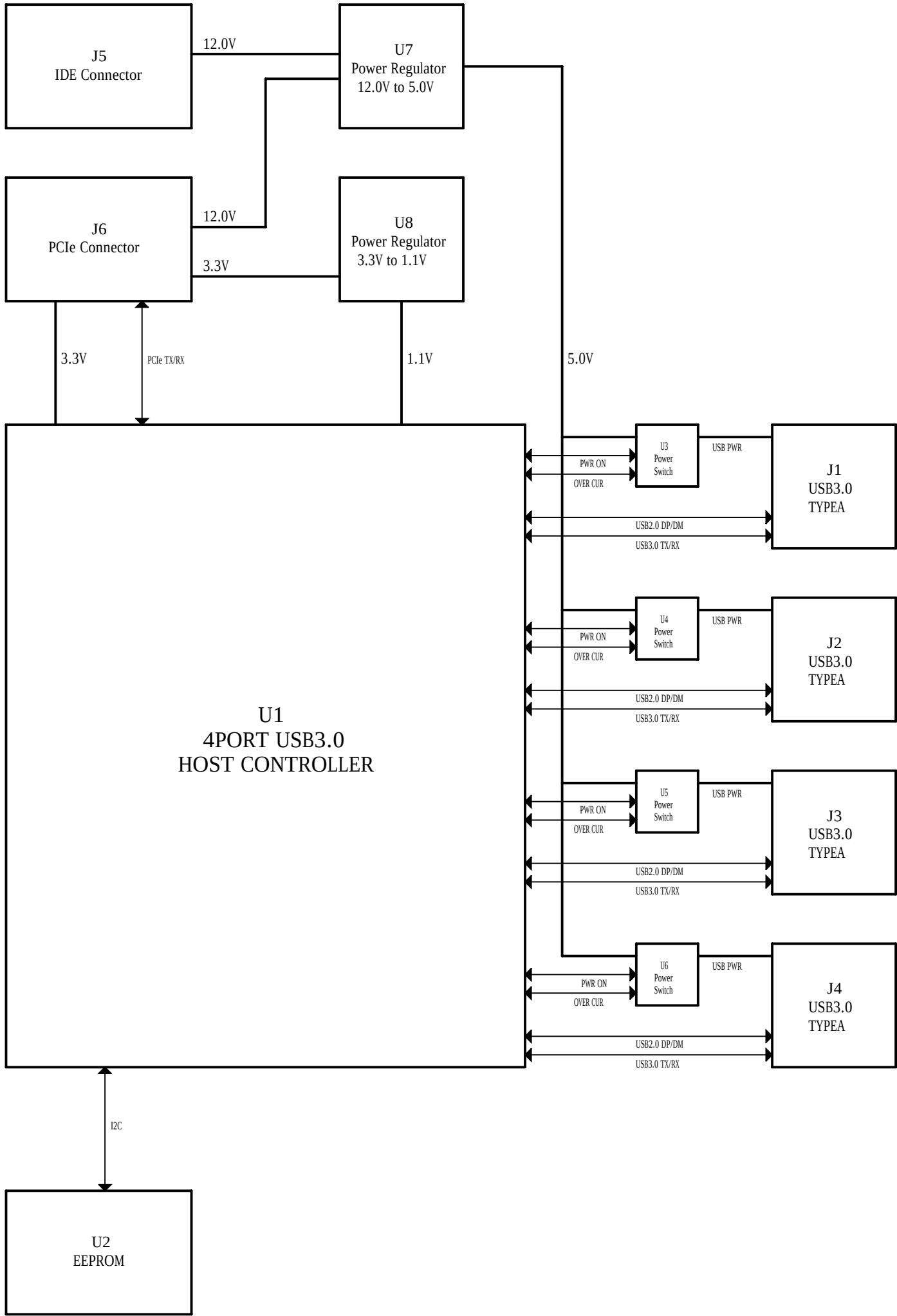
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REVISION NOTE				
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⚠	-	-	-	-



1. VIA AND TRACE:

- Min via pad size 20mils (0.508mm)
- Min spacing between trace and pad is 5mils (0.127mm)
- Min spacing between via and pad is 5mils (0.127mm)
- Min width of trace is 4mils (0.102mm)

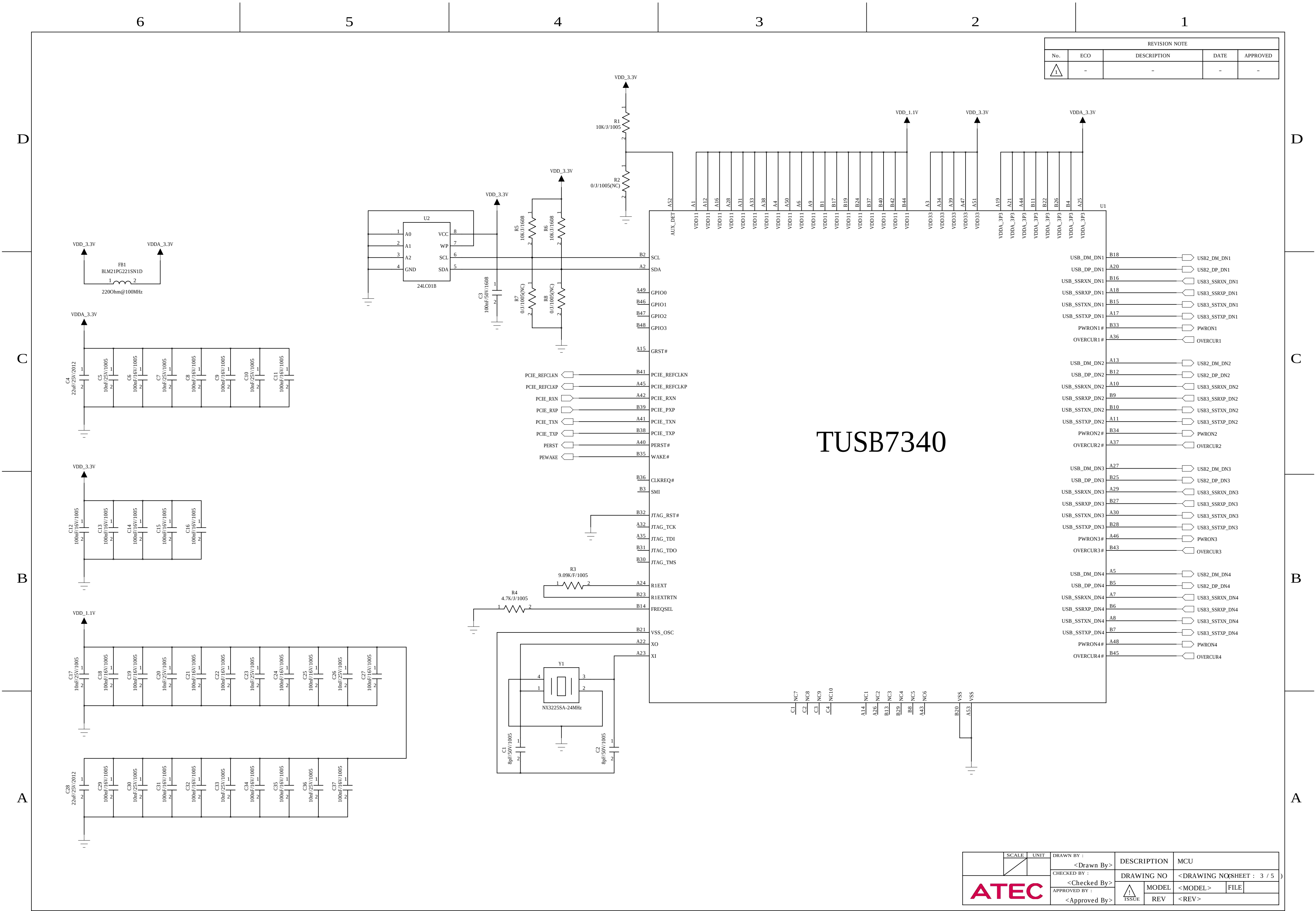
2. IMPEDANCE MATCHING:

- USB2_DP/M must be 90ohm differential (+/-15%)
- USB3_SSTXP/N must be 90ohm differential (+/-15%)
- USB3_SSRXP/N must be 90ohm differential (+/-15%)
- PCIE_TXP/N must be 100ohm differential (+/-10%)
- PCIE_RXP/N must be 100ohm differential (+/-10%)
- PCIE_REFCLKP/N must be 100ohm differential (+/-10%)

3. LINE LENGTH MATCHING:

- USB_DP/M within 25mils (0.635mm)
- USB_SSTXP/N within 5mils (0.127mm)
- USB_SSRXP/N within 5mils (0.127mm)
- PCIE_TXP/N within 5mils (0.127mm)
- PCIE_RXP/N within 5mils (0.127mm)
- PCIE_REFCLKP/N within 25mils (0.635mm)

ATEC	SCALE	UNIT	DRAWN BY :		DESCRIPTION	BLOCK_DIAGRAM		
			<Drawn By>					
			CHECKED BY :		DRAWING NO	<DRAWING NO&SHEET : 2 / 5 >		
			<Checked By>					
			APPROVED BY :		MODEL	<MODEL>	FILE	
			<Approved By>		ISSUE	REV	<REV>	



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ATEC	SCALE	UNIT	DRAWN BY : <Drawn By>		DESCRIPTION		MCU	
			CHECKED BY :	DRAWING NO		<DRAWING NO>SHEET : 3 / 5		
			<Checked By>		1 ISSUE	MODEL	<MODEL> FILE	
			APPROVED BY : <Approved By>			REV	<REV>	

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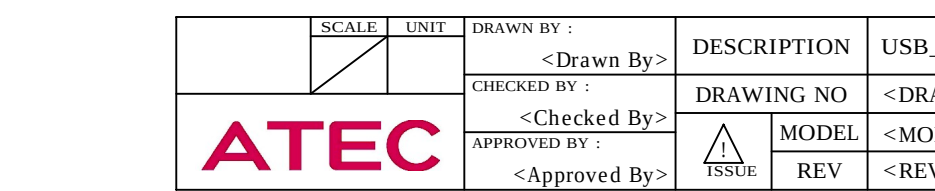
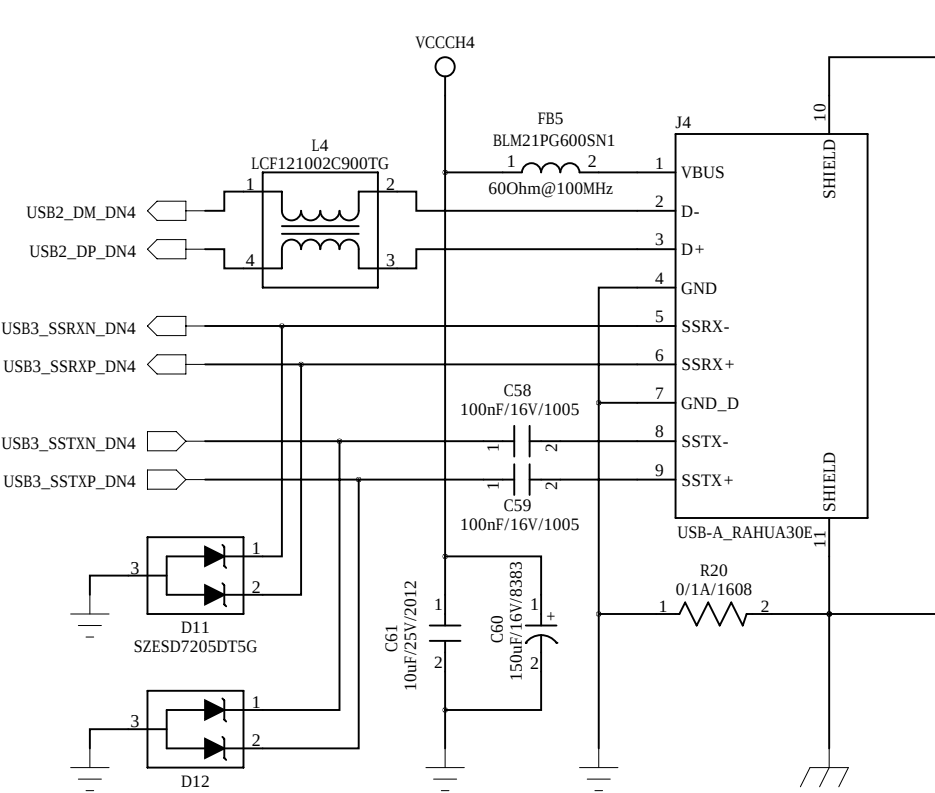
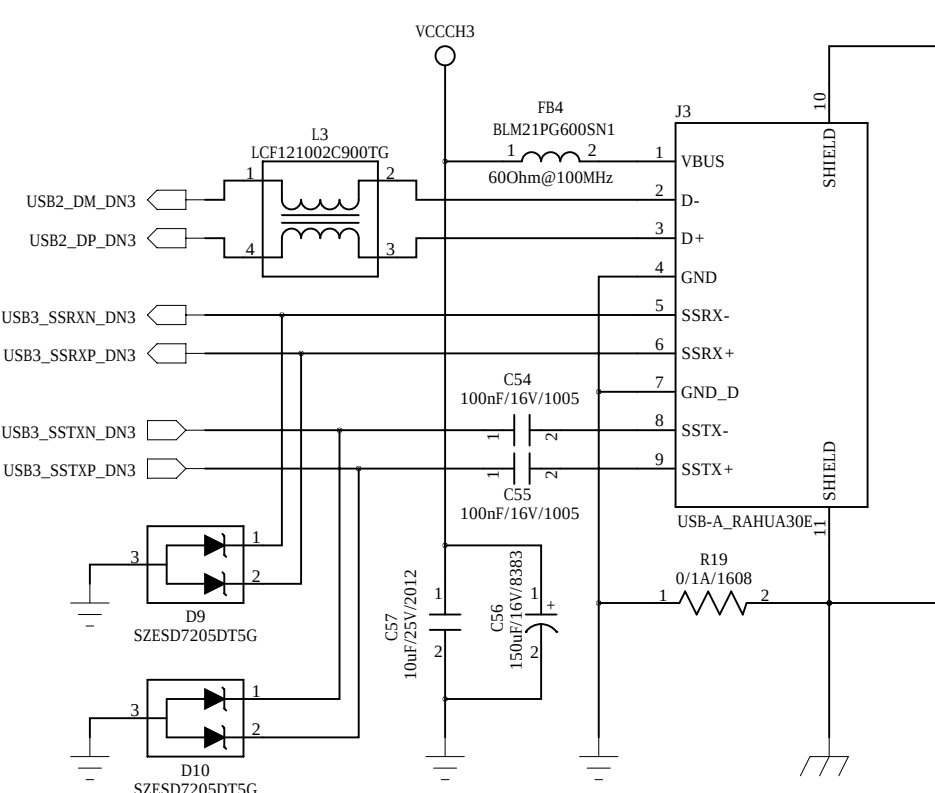
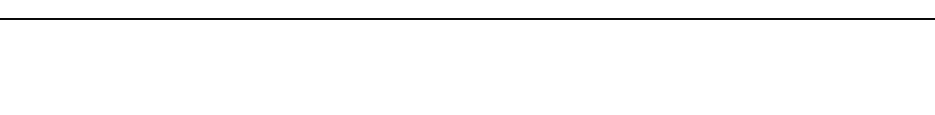
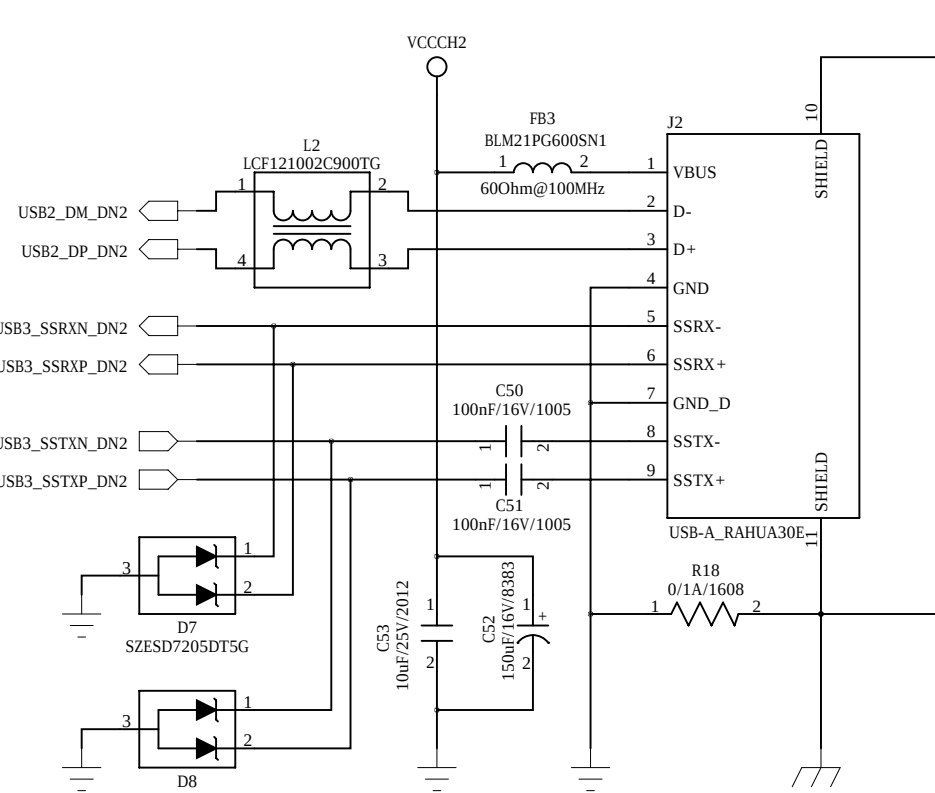
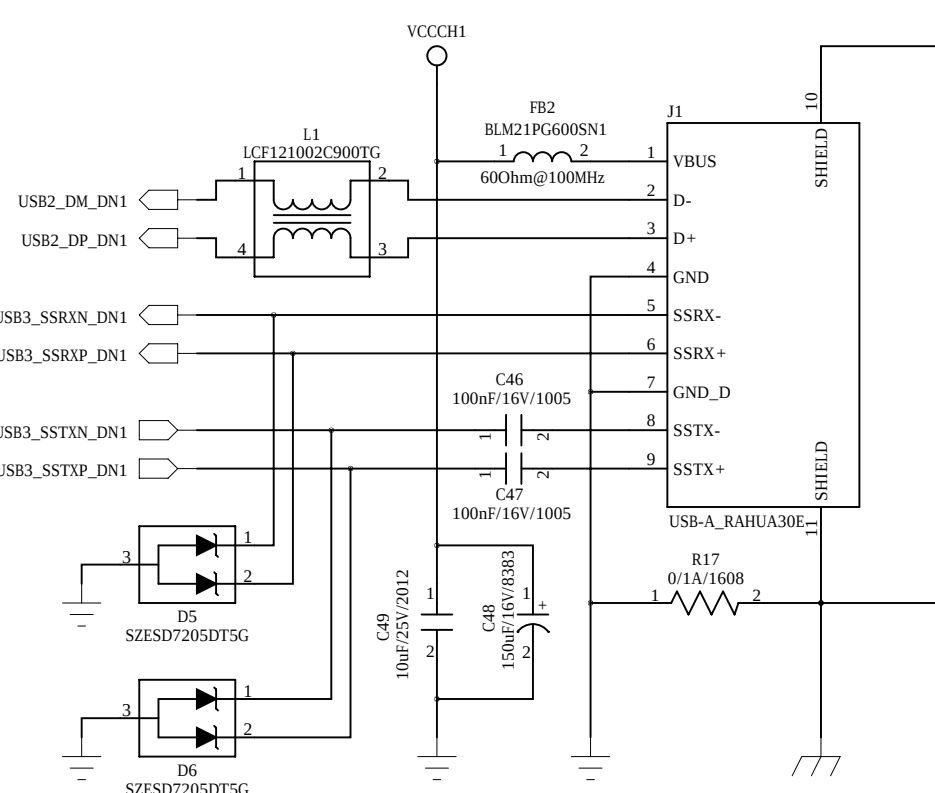
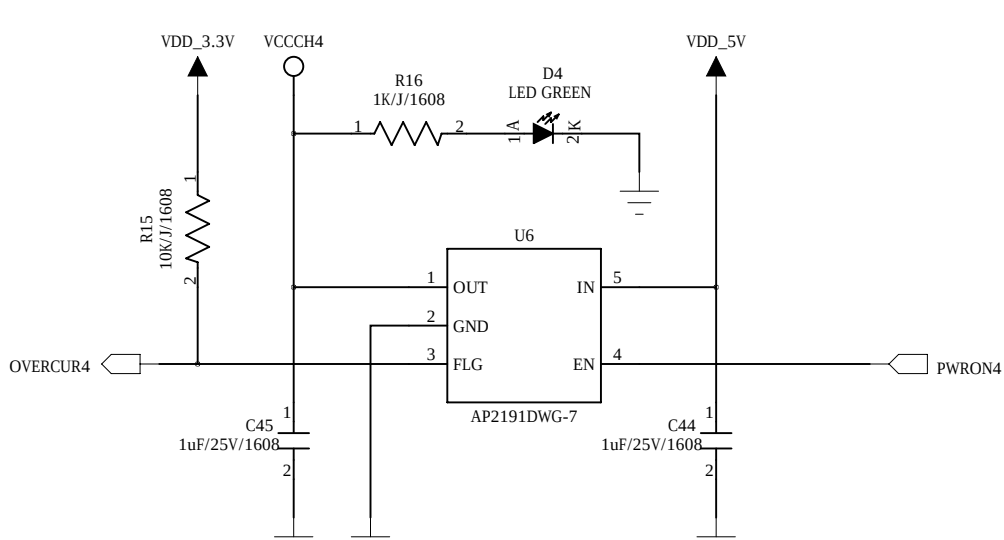
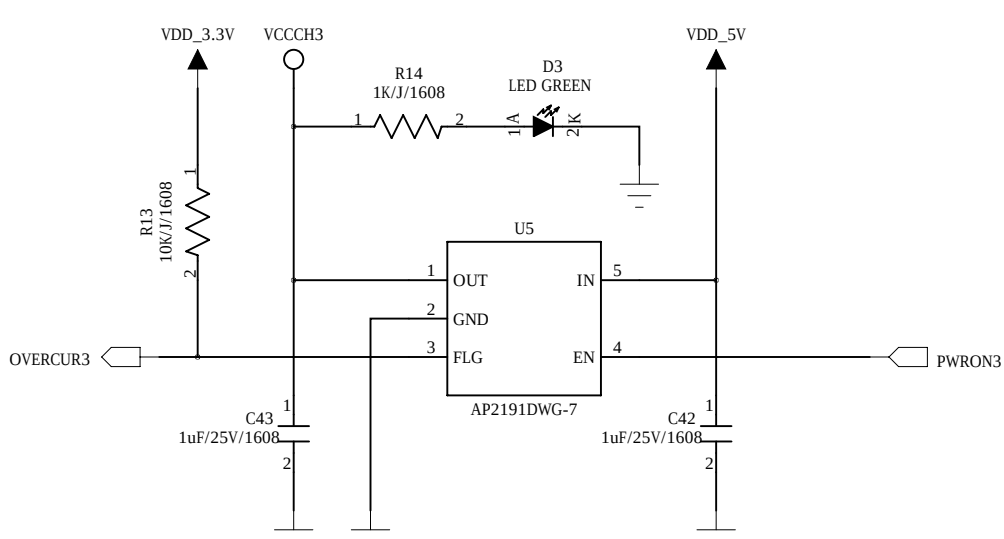
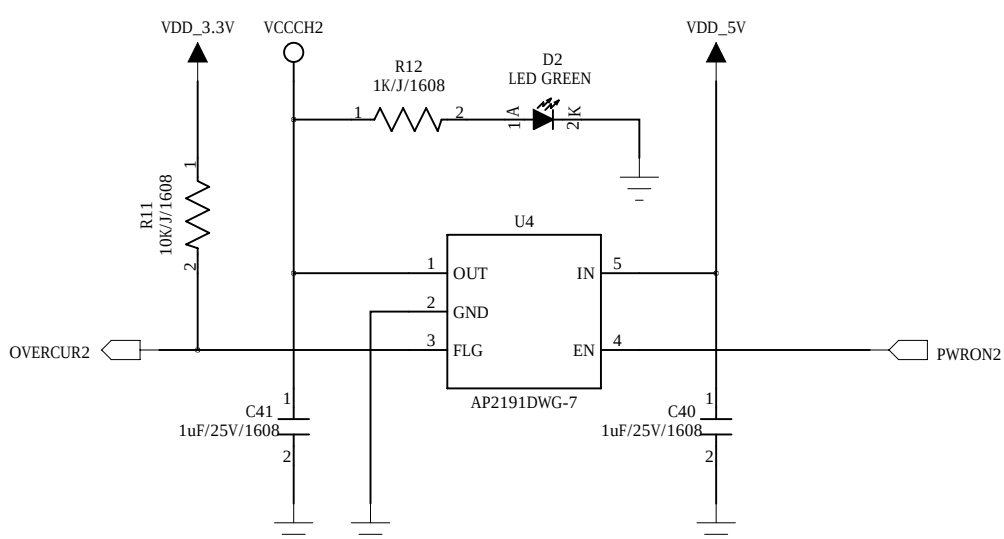
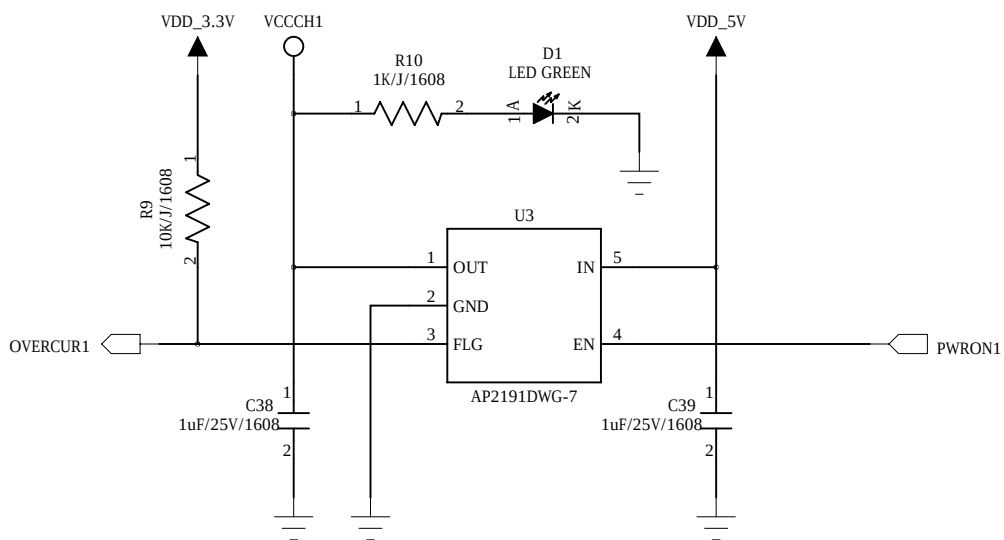
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REVISION NOTE				
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SCALE		UNIT	DRAWN BY :		DESCRIPTION	USB_HUB	
			<Drawn By>				
			CHECKED BY :		DRAWING NO	<DRAWING NO>SHEET : 4 / 5	
			<Checked By>				
			APPROVED BY :		MODEL	<MODEL>	FILE
			<Approved By>		REV	<REV>	

